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Study of Intermittent Field Hardware Failure Data in Digital Electronics

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NSN-29746#

STUDY OF INTERMITTENT FIELD HARDWARE FAILURE DATA IN DIGITAL ELECTRONICS Edward J. O'Neill and James R. Halverson Sperry Univac

1.0 Summary

Under this contract (NASA Contract NAS 1-15574) Sperry Univac was asked to investigate their data recording and retrieval system for failures of an intermittent nature that occurred in field operation. Due to the nature of an intermittent problem and the reporting of the problem being at the discretion of the user, data referring to the first manifestation of an intermittent failure is not available. However, Sperry Univac developed a list of failure mechanisms that could manifest themselves as intermittents. This list was used to retrieve, from the data system, those failures and their times that could be the final manifestation of a previously intermittent problem.

Three time periods were studied and probability functions were fitted and tested for goodness of fit to the data of intermittent and potentially intermittent failures. This was done for the computer and for the SSI digital microcircuit components.

Results show that the exponential model of time to intermittent failure is adequate for the microcircuits. However, the Weibull distribution gives a slightly more accurate fit in some time periods. The results from the different time periods indicates that the failure rate for intermittents increases as the age of the microcircuits increases. However, it is felt that the further investigation of larger time periods is necessary to confirm the results indicated in this study.

2.0 Introduction

2.1 Introduction

Intermittent hardware failures are known to have an important impact on the reliability of digital systems. However, accurate intermittent failure models of the type required to make realistic reliability assessments are not readily available. This study makes available a data base of intermittent failure information, based on field failure data, which were classified by failure mechanisms and their likelihood of having been intermittent (quasi-intermittent).

This study will direct its attention toward actual failures that occurred in field-installed hardware and were introduced into our failure analysis cycle. This approach, while limited in the total population of failures, provides a new data base of quasi-intermittent failure data for possible application to future reliability assessments.

2.2 Study Objective

The objective of this study is to develop a data base of information, based on available field failure data, for intermittent digital hardware failures.

2.3 Study Plan

To meet this objective this study will i) define the problem of intermittent failure, ii) describe Sperry Univac's data recording

and retrieval system, iii) study the problem at the computer level and iv) study the problem at the micro circuit-device level.

3.0 Study Definition

3.1 Intermittent Definition

An intermittent is defined as a detected malfunction of a logic net which was operating properly prior to the malfunction and resumes normal operation in less time than the time needed to isolate the malfunctioning net to the lowest replaceable unit (LRU).

In presently deployed computers, the time to isolate is of critical importance; that is, the time for the maintenance technician or the Built-in-Test (BIT) logic to find the problem and replace the component.

The impact of the duration of intermittency of any given malfunction and its frequency are dependent on the system architecture, software, and maintenance tools.

In older systems, and to some extent the systems of today, the intermittent was always detected by the operating software. The maintenance technician was then called and by utilizing his tools, i.e., test programs, scope, VOM, etc., he was expected to recreate the detection scenario and isolate the problem to some LRU. In this case, any intermittent with a duration of less than, say, 30 minutes, would not be isolated and would be declared an intermittent thus remaining in the system to cause trouble when it again fails.

In some present day equipment and potentially most new equipment, the task of both intermittent malfunction detection and isolation will fall upon BIT. If BIT were designed to

constantly monitor all logic nets, the detection and isolation of malfunction would occur almost instantaneously. This would mean that only malfunctions having a duration of a few nano-seconds would be classified as intermittent.

The definition of the duration of an intermittent has been specifically bounded by malfunction isolation time. This is due to the assumption that once the malfunction has been isolated and, consequently, removed from the system, the fact that the replaced item may once again resume normal operation is of no consequence to the system operation. This does, however, pose a significant problem for the failure analysis task.

3.2 Constraints on the Study

Historically, Sperry Univac has not maintained a data base of intermittent malfunctions. This is due to the following reasons:

Most of Sperry Univac's exposure to the system is that of equipment checkout. Once the equipment is running properly, it is delivered to the customer. The checkout time is but a small fraction of the total system life cycle and, as such, the quantity of intermittent failures experienced is very minute. Only with the advent of such activities as the 1000 hour burn-in testing, has the quantity of intermittents and the re-

porting structure been sufficient to justify the recording of intermittent malfunction data.

The field failure reporting has been at the customers' discretion. The failure data reported from the field is made up almost exclusively of hard failures. Due to the complex nature of customer operational software and customer hardware configurations, of which Sperry Univac normally provides only the computer, it is most likely that intermittent failures (particularly those with long time between manifestations) are rarely isolated and consequently not reported in the field unless they become hard or their frequency increases to the point where they appear hard.

Due to the lack of data on isolated intermittent failures as explained above, the only method of arriving at a data base pertaining to intermittent failures was to examine the reported hard failures and decide which failure mechanisms could manifest themselves as intermittents. This decision was arrived at by a joint effort by engineering personnel from the Sperry Univac Product Reliability Department and Failure Analysis Laboratory. Each failure mechanism was examined and placed in one of the following categories based on the best judgement of the above mentioned departments:

Intermittent - A relatively high possibility of
causing intermittent hardware failure.

Potential Intermittent - Some possibility of causing intermittent hardware failure.

Hard Failure - Little possibility of causing intermittent hardware failure.

Due to the lack of empirical data, the above failure categorization was accomplished by engineering judgement. Confidence in this categorization will be maintained until data is available to either confirm or reject any of these judgements.

Due to these constraints and the data base that was available for this study, all reporting and analysis of failures in this study are on field failures after they became hard.

4.0 Description of Sperry Univac's Failure Reporting System

4.1 Fail Codes

In Sperry Univac's failure reporting system there are 174 fail codes used to describe the failure mechanism. These refer to failures of an electrical, magnetic, electro-magnetic, and mechanical nature. Of these 174 codes, 43 are not applicable to this study, 86 would be considered "hard", 28 are considered potentially intermittent, and 17 are considered intermittent according to the definition of these classes in 3.2. A brief description of the codes that were intermittent or potentially intermittent are given in Figures 1-5.

Some contracts on individual computers call for the reporting of field equipment utilization, failure reporting, and failure analysis. The data on these computers goes into Sperry Univac's failure reporting system.

4.2 Reporting Forms

The sources of the data for this study utilized three reporting forms. The first is an "Equipment Utilization Report". (See Appendix A.1.) This report is filled out monthly for each equipment that is participating in the utilization reporting program. This report is used even if the equipment does not experience any

POTENTIALLY INTERMITTENT

Fail Code Description

- 10D Broken Weld: possible intermittent operation resulting from partial contact of wire to pad.
- 11F Smeared Open Chip Bond: possible intermittent failure resulting from partial electrical contact of the lead wire to the bond pad or bond to adjacent metal.
- 11G Smeared Open Post Bond: possible intermittent failure resulting from partial electrical contact of the lead wire to the bonding post.
- 11L Bond Short to Metallization or Chip Edge or Mislocated: possible intermittent operation caused by partial shorting of the wire bond to metal interconnects or adjacent bond pads.
- 12G Interlayer Metal Short: possible intermittent operation resulting from partial shorting of metal interconnects (used for multi layer metal devices).
- 13C Cracked Die: possible intermittent failure resulting from partial electrical contact of the parts of the semiconductor die.
- 15A Out of Spec(Elect): possible intermittent operation resulting from out of specification electrical parameters; this is dependent upon operating design margins.
- 15E Slow Recovery: possible intermittent operation caused by slow reverse recovery (Trr) of diodes; this is dependent upon the design operating margins.
- 15F Core Cracked/Defective/Noisy: possible intermittent operation caused by cracked/defective/noisy cores resulting in bits being "picked" or dropped.

POTENTIALLY INTERMITTENT (continued)

- 15G Early Peaking Core: possible intermittent operation caused by an early loss of core signal output; this is dependent upon the design operating margins.
- 20K Timing Delay Line Taps: possible intermittent operation caused by out of specification timing adjustment of delay line.
- 21A Delay Time: possible intermittent operation caused by out of specification delay time of printed circuit assemblies or subassemblies.
- 21L Low Output: possible intermittent operation caused by an output signal which does not achieve the specified output level.
- 21M Magnetostriction: possible intermittent operation caused by a change in electrical characteristics (e.g. ringing) of a core caused by excessive external pressure.
- 22H Not Verified, Elect cause unknown
- 22J Not Verified, Elect plating anomolies
- 22K Not Verified, Elect restriction of wire
- 22L Not Verified, Elect scratch/abrasion
- 22M Not Verified, Elect bond
- 22N Not Verified, Elect corrosion
- 22P Not Verified, Elect substrate defects
- 22Q Not Verified, Elect nonrestrict foreign material
 Failures with the above fail codes could be considered to
 cause possible intermittent operation since a failure was
 experienced for which no cause could be determined but only
 suspected.
- 23B Noisy Bit: possible intermittent operation caused by excessive noise, ringing, excessive recovery, or impedance mismatch of a core or film output signal.

POTENTIALLY INTERMITTENT (continued)

- 23K Weak Bit: possible intermittent operation caused by a narrow output pulse or an output level below that for system operation (see 21L).
- 31A Unverified failure
- 31C No defect found by failed item analysis
- 31H Unverified failure/suspect part replaced
- 3lJ Scrap-unverified failure

 Failures within the above codes could cause intermittent

 operation since a failure did exist which could not be veri
 fied through failure isolation.

INTERMITTENT

- 10G Shorted Lead Wire, Poor Lead Dress: intermittent shorting to the edge of the die or adjacent wire bonds.
- 10L Internal Particle or Contamination: intermittent shorting between die metallization stripes, bonding ponds/wires or edge of die to package.
- 10N Lead or Metal Migration (Grow Back): intermittent contact of metal links, originally fused to create an open (logic "1"); this is used primarily for PROM's with fused link technology.
- 11D Plagued Open Chip Bond:
- 11E Plagued Open Post Bond: intermittent open of the chip or
 post bond resulting from the formation of "purple-plague"
 in Au-Al intermetallic systems.
- 11H Underbonded Chip Bond:
- 11J Underbonded Post Bond: intermittent open of the chip or post bond resulting from inadequate ultrasonic bonding interface in Al-Al systems.
- 12B Open Metallization Due to Microcrack: intermittent open of metallization stripes, primarily over ohmic steps, resulting from discontinuous (cracked) metallization.
- 12C Open Metal Electromigration: intermittent open metallization due to migration within thin areas of metal stripes caused primarily a combination of excessive current density/temperature.
- 15M Pattern Sensitive: intermittent logic failure resulting from a particular pattern within memory causing an undesired change of memory bit (primarily used for RAM's).
- 20B Bent, Broken or Pushed in Pins: intermittent open contacts resulting from damged connector pins.

INTERMITTENT (continued)

- 20C Cold Flow, Abraded or Damaged Wire Insulation: intermittent shorting resulting from damaged wire insulation causing shorts to adjacent connector pins, wires, terminals or ground.
- 20F Warped, Splitting, Uneven Mat Area: intermittent electrical failure caused by a change of magnetic core characteristics or core damage resulting from warped, split or uneven core mat.
- 21G Damaged Foil: intermittent open caused by raised or damaged metallic interconnects (foil) on a printed circuit card.
- 23G Disturb: intermittent logic failure within memory resulting during a READ or WRITE cycle at one location causing another location to change states.
- 30H Reseated Cards: intermittent failure resulting from improperly or unseated printed circuit cards causing intermittent connection.
- 31D Intermittent/Cause Unknown: intermittent computer, assembly or sub-assembly failure experienced for which no specific cause could be established.

failures. When a computer, which is covered by this reporting system experiences a failure and the failure results in a repair, it is reported on either a, "Failure/Malfunctional Report" (FMR), or an "Equipment Malfunction Report" (EMR). See Figure A.2 and Figure A.4 for the format of these reports. Figures A.3 and Figure A.5 of the Appendix A give the explanation of the fields contained in the reports. When an EMR or FMR is filled out, the failing assembly and the form are sent back to the factory. The failing assembly is analyzed to determine the cause of the failure. The information on the report is then entered into a data base. All of the computers using the utilization reporting system use the FMR or the EMR; however, all of the computers using the FMR or EMR do not use the equipment utilization report. Part of this study required that the number of computers under investigation be known for each time interval. This is the reason that only the 169 computers that are in the field utilization program were used in the distribution analysis.

An example of the raw failure data is given in Figure 6. This failure was isolated to a control memory printed circuit card in the field. The failure analysis laboratory determined that the failure was in the integrated circuit at location 16 on the card and that the failure mechanism within the chip was open metal electromigration (12C). The FMR and EMR both contain a block within field 36 to explain the observed failure characteristics;

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"INTERMITTENT" is one of the possible characteristics to check in this block. Unfortunately, reporting in this block has been erratic and this block was not entered into the data base. This is the reason the failure mechanism was used to define which failures have been intermittent prior to going hard.

Once the EMR and FMR are completed, the data is entered into Sperry Univac's reporting and retrieval system. The computer file has, theoretically, a field for every block of data on the EMR or FMR. The failure data can be sorted and ranked by the fields in any order that the user wants. This allows for quick and easy access to the specific information that the user wants. An example of retrieval data is given in Figure 7.

4.3 Components

A brief description of the components that Sperry Univac uses is as follows:

- Integrated Circuits: The integrated circuits used are purchased to Sperry Univac specifications which require processing, inspection and both screening and sample testing in accordance with MIL-M-38510, and MIL-STD-883 for Class B devices.
- 2) <u>Semiconductor Devices</u>: The semiconductor devices used are purchased to Sperry Univac specifications which require processing, inspection and both screening and sample testing in

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accordance with MIL-S-19500 and the applicable slash specs for JAN TX devices.

3) <u>Passive Devices</u>: The majority of the passive devices used are MIL or ER equalifiers and are purchased to the applicable military specifications.

4.4 Data Base

Sperry Univac had four programs in the above data reporting system which were applicable to this study. The application of these programs were two shipboard, one submarine and one avionics. For these programs approximately 21,000 field failures were on file from the past five years. However, not all the failures in this data base were reported with the time of failure (Elapse Time Meter). In addition, the reporting system is dynamic with computers of all age groups being included. It was decided to concentrate upon the one ship-board program that made up the majority of the failures and the population of computers in our data base. To address the problem of changes in the occurrence of failures over time, it was decided to "freeze" the data base into three time periods and to include a computer in the time period only if that computer ran throughout the entire time period.

4.5 Computer Description

The computer which yielded sufficient data for use in this study

is a highly reliable, ruggedized multiple-processor system designed by Sperry Univac for military applications. To meet stringent environmental and functional specifications, this computer was designed to meet MIL-E-16400 (ship and shore) environmental requirements. Other specifications and standards used for design objectives are as follows:

Radio Frequency Interference: MIL-I-16910

Shock: MIL-S-901 Class I Medium Weight

Vibration: MIL-STD-167 Type I

Salt Spray: FED-STD-151 Method 811

Environmental Characteristics:

Temperature Range:

-54^OC to +65^OC (Operating)

-62°C to +75°C (Storage)

Relative Humidity to 95%

This computer is comprised of one or more of each of the following modules:

Central Processor

Input/Output Controller

Memory

Input/Output Adapters

Power Supplies

With the exception of the power supply, each module has a wirewrapped back panel terminating in receptacles that mate with the male connectors on the printed circuit cards and memory modules. All heat dissipated by circuit elements is transferred to the top of the card or memory assembly by thermal conduction to metallic "T" bars. The assembled module is closed by a heat-exchange cover which makes thermal contact with all "T" bars. Ambient air drawn through the heat exchanger by the cabinet cooling system removes heat to the outside.

Man/Machine interface for maintenance actions is accomplished via a maintenance unit panel which provides operation controls and indicators which present internal computer register values needed to isolate printed circuit card failures.

This computer is presently in operation in both shipboard and shore based applications. Due to the reporting structure comprising the data base available to Sperry Univac, only the shore based computers are involved in this study. The environment of the study-related computers is that of normal commercial computer center operations. This implies ambient air temperatures of 70°F to 80°F with no shock or vibration exposure.

5.0 Study at the Computer Level

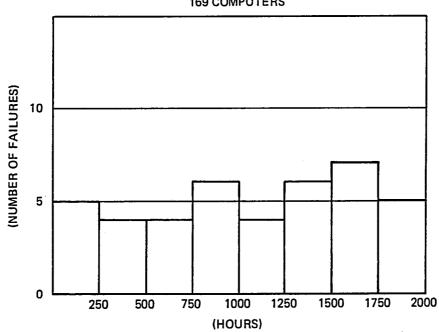
5.1 Histograms

All discussion that is to follow refers to the one computer discussed in Sections 4.4 and 4.5. The failure data was put into histograms for the following running time periods: 10,000 hours, 5,000 hours, and 2,000 hours. These histograms reflect the hard failures, intermittent failures, and potential intermittent failures for that period. The data for the three time periods is based on a fixed number of computers for each period. The following is that relationship.

Time Period	Number of Computers		
0 - 2,000 hrs	169		
0 - 5,000 hrs	116		
0 - 10,000 hrs	48		

These histograms are shown in Figures 8 through 16. The data has been screened to eliminate failures which may skew the data. In addition, the screening determined that if a computer had more than one failure, they occurred in different modules and at different times so that the failures can be assumed to be independent. The data represented in these histograms represents the first look at the computers in the reporting system. They have one limitation in that the failures are grouped in 250-hour blocks of time and that it was not possible to obtain raw data for this portion of the study. An interesting observation is that no intermittent failures were observed after 8000 hours. Appendix B.2 has the breakdown by time periods.

INTERMITTENT FAILURES 169 COMPUTERS



POTENTIALLY INTERMITTENT FAILURES 169 COMPUTERS

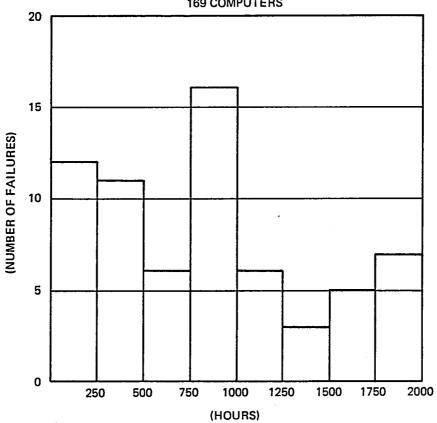


FIGURE 8.

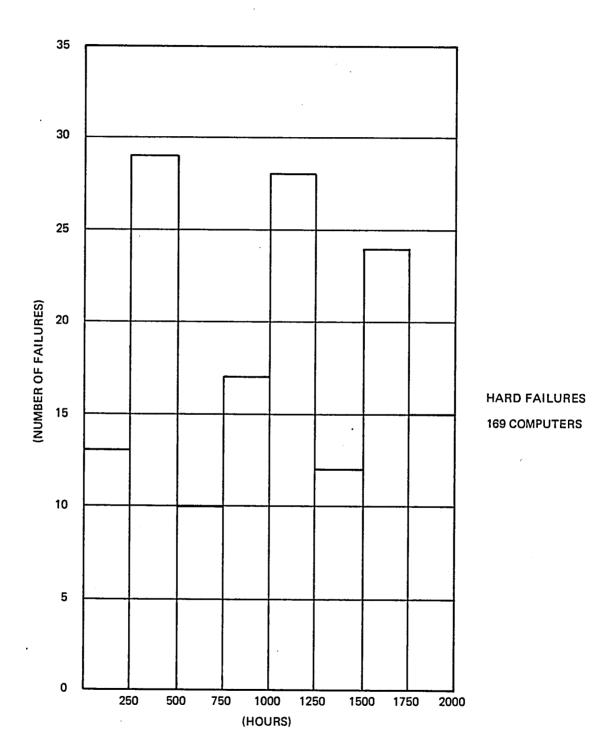


FIGURE 9.

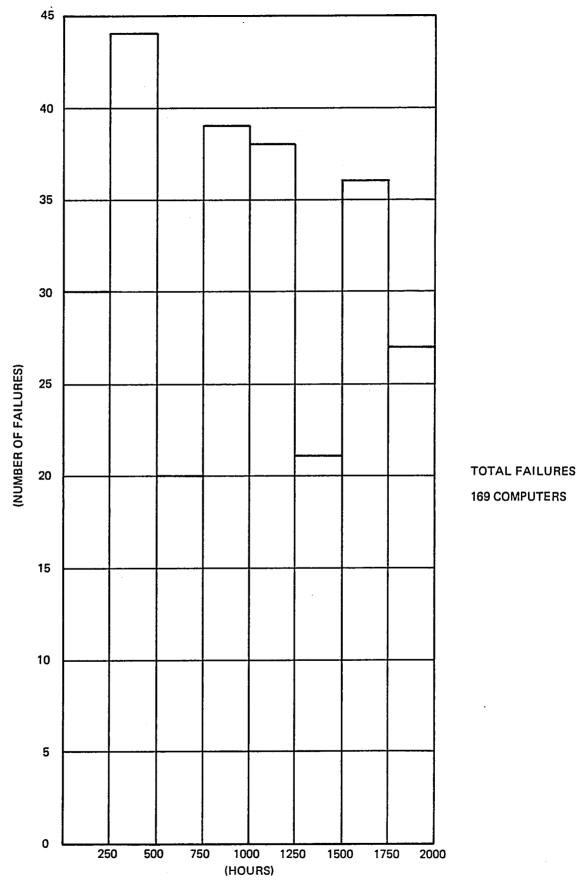
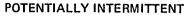
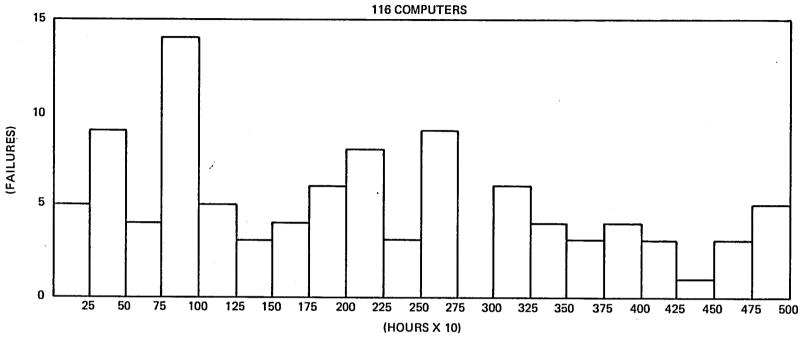


FIGURE 10.





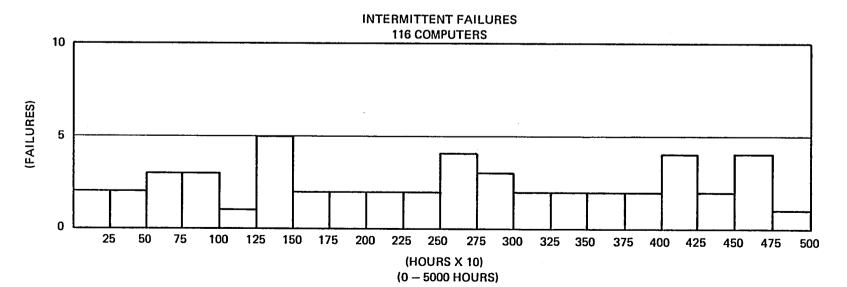
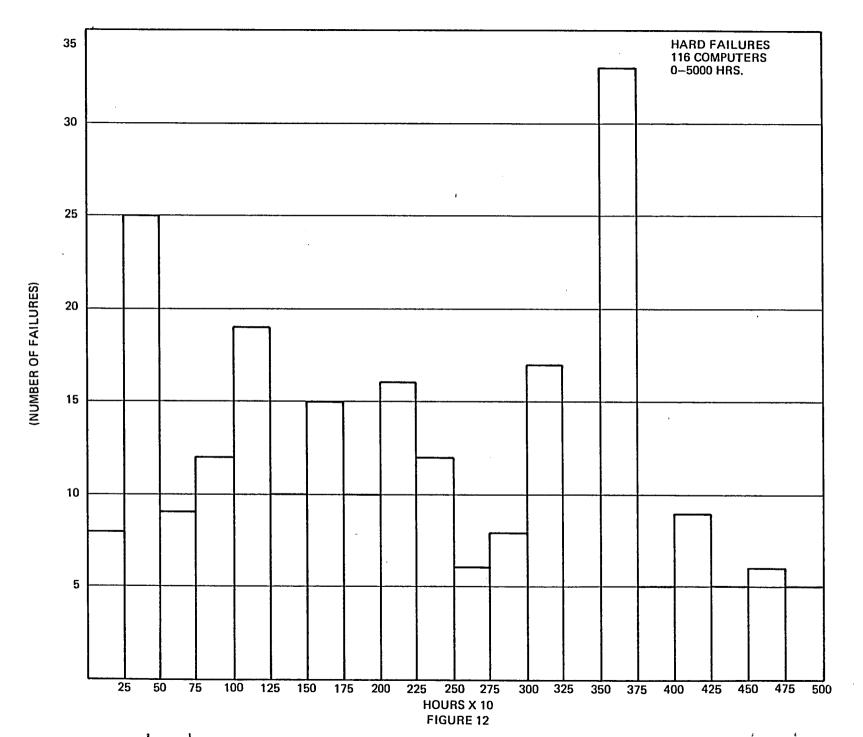
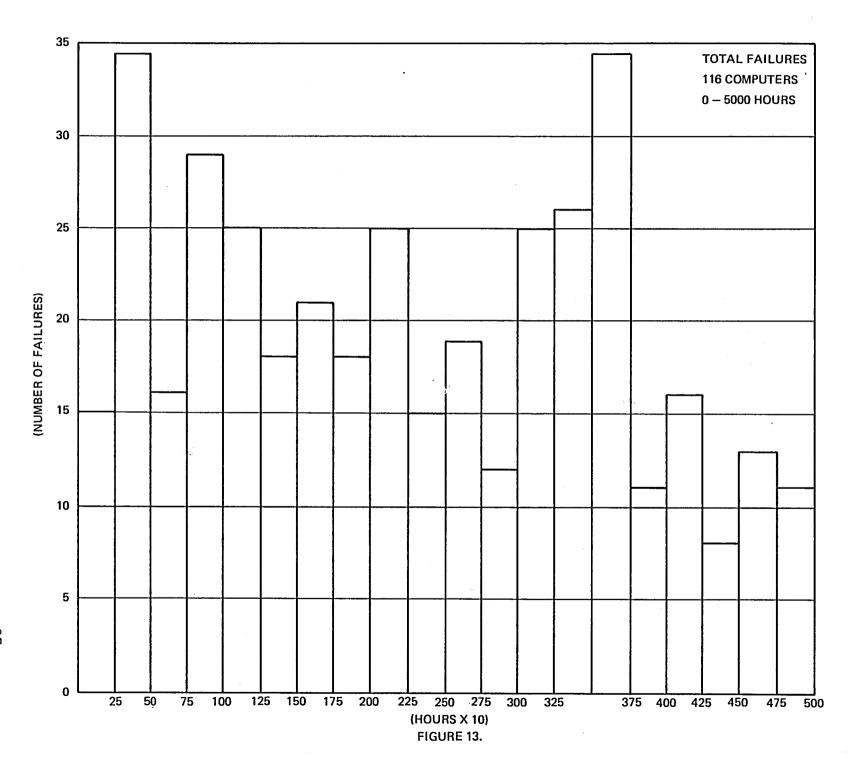


FIGURE 11.

25





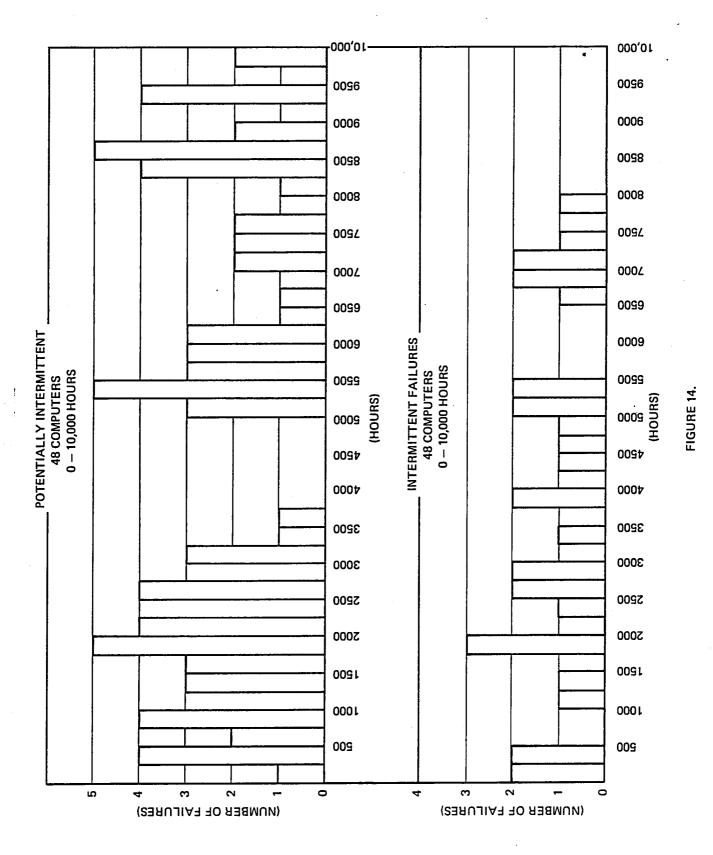
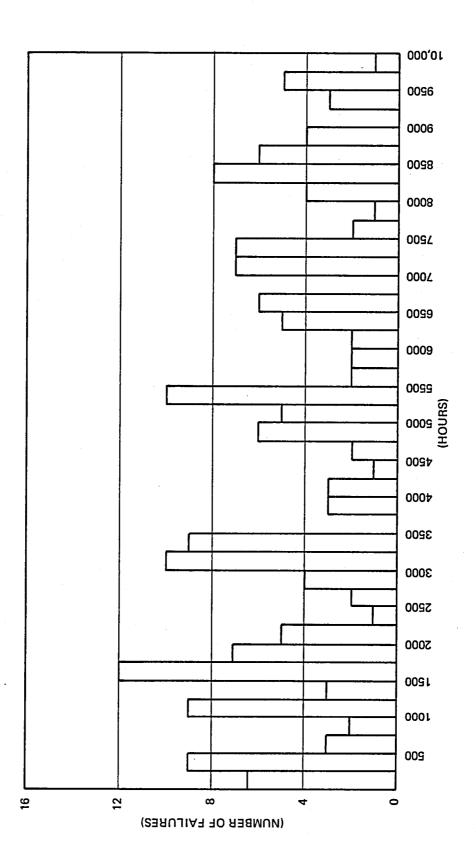


FIGURE 15.



HARD FAILURES 48 COMPUTERS 0 – 10,000 HOURS

5.2 Analysis

The failure data presented in these histograms was analyzed with respect to time to failure. Figure 17 lists the distributions functions for time to failure. In Appendix B.3, confidence intervals for the mean time to failure for the exponential distributions are given. The special form of the distribution for potentially intermittent failures in 0-10,000 hours (see Figure 14) suggests considering the time intervals 0-5000, 5000-8250, and 8250-10,000 separately when determining confidence intervals for the parameters; this is what was done in Appendix B.3.

For the Weibull distribution, confidence intervals for the parameters require the data to appear in ungrouped form which was not available. However, since the rank distribution of failures follows a beta distribution, confidence intervals for the fraction of failures are possible for the Weibull cases. At each time listed, there is a 90% chance that the fraction of failures that have occurred will be between the two values given. For example: In the potentially intermittent failures 0-2000 hours, one would expect by the time of 1000 hours between 27 and 32% of the failures to have occurred with a confidence of 90%.

5.3 Procedure

The first attempt in all cases was to fit an exponential distribution to the data. The estimate of the mean time to failure was total test time/total number of failures. The Chisquare test for goodness of fit was then used. For those distributions where the fit was poor, a Weibull distribution fit was attempted. To fit the Weibull, the data was ranked. Because the data was grouped, it was assumed that the last failure in each time interval occurred at the endpoint of the time interval.

The estimates of the Weibull shape and scale parameters were taken from the best fitted line of ln (Time to failure of cumulative ith failure) -vs-ln ln ((l-(Cumulative ith failure-.3)/(n+.4))-l). The criterion for testing the Weibull distribution fit was the Kolmogorov-Smirnoff Statistic.

For the 0-10,000 hour distributions the limitations of Chisquare goodness of fit test became apparent. The test is sensitive to the number of cells used, the expectation of each cell, the expectation varying from cell to cell, the sample size, and the testing of a continuous distribution. For the 0-10,000 hour intermittent, it was difficult to obtain a constant expectation from cell to cell or an expectation of at least 5 for the potentially intermittent failures. An alternative that is recommended in the literature is the Kolmogorov-Smirnoff test for goodness of fit. The theory has been developed, however, for ungrouped data and limited results are available in the literature for grouped data for 30 or less observations. There is a procedure to obtain a conservative upper bound on the Kolmogorov-Smirnoff statistic, Dn, when the data is already grouped. This procedure follows:

Let F_i refer to the observed cumulative distribution value of the ith cell and F_i the fitted cumulative distribution value at the right end point of the ith cell $i=1,2,\ldots n$. Let $F_o=F_o=0$. Observe that for each cell and every x that is sampled from that cell:

$$F(x) - \hat{F}(x) \leq F_{i} - \hat{F}_{i-1} \quad \text{if } F(x) \geq \hat{F}(x)$$

$$(1) \hat{F}(x) - F(x) \leq \hat{F}_{i} - F_{i-1} \quad \text{if } \hat{F}(x) \geq F(x)$$

Hence for the ith cell:

(2) Max
$$\left\{\max((F(x) - \stackrel{\wedge}{F}(x)), \stackrel{\wedge}{(F(x) - F(x))}\right\} \leq \max((\stackrel{\wedge}{F}_{i} - F_{i-1}), (\stackrel{\wedge}{F}_{i-1}))$$

 $x \in ith cell$

But this can be rewritten as:

(3)
$$\operatorname{Max} \left| F(x) - F(x) \right| \leq \operatorname{Max} \left(\left(F_{i} - F_{i-1} \right), \left(F_{i} - F_{i-1} \right) \right)$$

$$x \in ith$$

$$cell$$

So finally:

(4) Dn = sup
$$|F(x)-F(x)|$$
 = max $(\max |F(x)-F(x)|) \le \max (\max (F_i-F_{i-1}), (F_i-F_{i-1}))$
x all $x \in i$ th cell all i cells

If the right hand side of (4) is less than a tables value of the Kolmogorov-Smirnoff statistic, then clearly $\mathbf{D}_{\mathbf{n}}$ is less by transitivity and the distribution would be acceptable as a good fit.

Figure 17 lists the fitted density functions that best describe the failure phenomenon of the computer. In addition we listed the values of the chisquare statistic and the upper bound for the Kolmogorov-Smirnoff statistic. The one situation where the Weibull and exponential fit was poor was the potentially intermittent 0-10,000 hour case. The data as seen in the histogram of Figure 14 suggests a multimodal distribution that repeats itself after 5000 and 8250 hours. A piecewise fitting by the potential distribution was attempted. The parameters were calculated by the statistic mentioned above. The constants a₁, a₂, a₃ are factors used to normalize the area under the pdf curve to 1. They are found by evaluating $x_i/n \neq \int_{t_i}^{t_i} f(t) dt$ where \boldsymbol{x}_{i} is the number of failures occurring in the time period (t_i,t_i) ,f is the density function for that time period and n is the total number of failures. The fit over the full 10,000 hours is acceptable.

5.4 Conclusion of Unit Study

The computers in each time period were in a repair mode, that is when a computer failed it was repaired and allowed to continue to run. The data was screened to insure that there was independence between failures in the same computer. The drawback is that the data was only available in grouped form. Another limitation is that the window size of units in the 0-10,000 hour time period, 48, was small and could lead to the pattern of failures that is seen in figures 14 and 15. This sample size magnitude for the

0-10,000 period makes the pdf's found for this period questionable. However, this sample size and their failures represent all the good data that Sperry Univac had available for this time period at the time this study was made.

The modeling of time to hard failures at the computer level was done when the data base was frozen and the failures of micro circuits was retrieved. The numbers of computers in each window are given in figure 18. The raw data of time to failure was available for this part of the study. The models of exponential or Weibull time to hard failure were rejected by the conventional tests of goodness of fit. Figure 17a summarizes the modeling that was done. It is seen that the MTBF is increasing as the age of the computer increases.

The pdf of fitted distribution of time to failure. "The X and D values should be compared with the tables of Chisquare and Kolmogorov-Smirnoff."

the ta	ables or Chisquare and R	OTWOGOTA - PWILLHOLD	• •
Description			m
Intermittent Fai	ilures pdf		Test for Accepting pdf
0 - 2000 hr.	$\frac{1}{8243.9}$ exp (-t/8243	.9)	λ(6) = 3.45
0 - 5000 hr.	$\frac{1}{11,600}$ exp (-t/11,6	00)	$\chi^{1}(10) = 4.18$
0 -10000 hr.	.9734 t0265 exp	-(t/9409) 9734 F	Colmogorov-Smirnoff D31 ≤ .0943
•			
Potentially Inte	ermittent	4 9305	Kolmogorov - Smirnoff
0 - 2000 hr. (412	.9305 t .0695 exp.	·(*/4129.08) · /303	D ₆₆ £ .0813
0 - 5000 hr.	1.23 t.23 exp. (3011.86)	· (t/ _{3011.86}) 1.23	^D 101 € . 1102
0 -10000 hr.	a ₁ /6858.71 exp (-t/6	858.71) 0 1 t 4 500	00 ·
	$\frac{a_2}{6000}$ exp = $\left(\frac{t-5000}{6000}\right)$	5000 s t < 8250	
	exp (+-8250 4941.2	8250 1 t < 10000	
	$a_1 = .866905$		
•	$a_2 = .7970245$		
	a _{3.} = .730778	ኢ ት(12) = 20.63

Figure 17

Description	CDF	MTBF
Hard Failures	F(+)	
0-2000 hr.	$04540523(\frac{t}{100})$.81	3663
6-5000 hr.	$1403 + .1069 \left(\frac{t}{100}\right)^{.62}$	4860
0-10,000 hr.	$1015 + .0940 \left(\frac{t}{100}\right).64$	5655

6.0 Microcircuit Failure Data

6.1 General Information

The data base was studied according to the three time periods—
0-2,000, 5,000 and 10,000 hours. Due to the dynamic nature of
the data reporting system, the numbers of computers in each
window changed slightly from when the study at the unit level
was made. The data base is composed of 196 computers that have
run at least 2,000 hours. Of these computers, 139 have run at
least 5,000 hours and 67 of these 139 have run at least 10,000
hours. The reference to failures in this paper refers to solid
failures that have been categorized by Sperry Univac into intermittent, potentially intermittent, and hard classes. For brevity
in the tables, these are referred to as I, II, and III respectively

There are 18 micro circuit types included in this study. These comprise all digital microcircuits of the computer of this study. The 18 types made up the population of 1,552,649 in the 0-2,000 hour period, 1,131,981 in the 0-5,000 hour period, and 528,577 in the 0-10,000 hour period. Of these 18 types, 8 types had no failures of any kind and were a total of 20,622 or 1.3% of the 1,552,649. For all failures, it was determined from the data base that no two microcircuits failed on the same card so that there is independence in the failures observed. The data base was also screened for failures that skewed the data, e.g. non-relevant overstress failures. Figure 18 summarizes the important information.

Time Period	# Of Computers	# Of : IC	# Of Most Failing Digital Device	# Of Intermittents	# Of Pot.Int.	# Of Hard
0-2000	196	1552649	58043	. 11	7	26
0-5000	139	1131981	42249	27	10	44
0-10000	67	528577	19637	8	8	35

Total of 103 failures

Part hours: 3.1053 X10 9 for 0-2000 hours

5.6599 X10. for 0-5000 hours

5.2858 X10⁹ for 0-10000 hours

Computers in the 0-2000 group with no IC Failure - 629,370 IC's Computers in the 0-5000 group with no IC Failure - 277,814 IC's Computers in the 0-10000 group with no IC Failure - 91,764 IC's

6.2 Analysis

The probability distribution functions for time to failure are in Figure 19. A comparison of the reliability functions according to the empirical, Weibull, and exponential distributions for each time period and failure type are in Appendix C. criteria for determining, from the results in Appendix C.1, which of the two distributions, Weibull or exponential, appears in Figure 18 are the precision and maximum error from the empirical data these two distributions have. For example, the Weibull distribution for the 0-5,000 II group has a maximum error of 1.2 failures while the exponential has a maximum error of four failures. For the 0-2,000 I, 0-5,000 III and 0-10,000 III, the Weibull distribution has a greater maximum error than the exponential. However, this error occurs towards the end of the time periods and the Weibull gives a consistently better fit than the exponential. Therefore, the Weibull distribution was used in Table C.

The Appendix C.1 suggests that the rate of change of intermittent failure rates is increasing while the rate of change of the hard failure rate is decreasing. One reason that the failure rate for 0-10,000 I is increasing is because the first failure occurs after 1,000 hours and all occur within the next 3,600 hours. This contrasts with the earlier time periods that had failures observed as early as 100 hours. Additional data would be necessary for the 0-10,000 time period to determine if the failure rate of solid intermittents is increasing. Appendix C.2 gives

FAILURE TYPE	TIME PEPIOD	DISTRIBUTION FUNCTION F(t)	DISTRIBUTION FUNCTION TYPE	HAZARD FUNCTION	MITF (IR)
I	0-2,000	$1-\exp{-\left(\frac{t}{9.254 \times 10^{11}}\right)^{.603}}$	Weibull	$\frac{.603 \text{ t}^{397}}{(9.254 \text{ x}10^{11})^{.603}}$	1.384 x10 ¹²
I	0-5,000	1-exp- $\left(\frac{t}{209,626,111}\right)$	Exponential	4.8 X10 ⁻⁹	2.096 x10 ⁸
ı	0-10,000	$1-\exp{-\left(\frac{t}{455\ 5450}\right)^{1.6017}}$	Weibull	1.6017 t .6017 (455 5450) 1.6017	4.08 x10 ⁶
	0-2,000	$1-\exp\left(\frac{t}{6.4228 \times 10^{10}}\right)^{7}$	Weibull	.7 t3 (6.4228 x10).7	8.13 X10 ¹⁰
II.	0-5,000	$1-\exp{-\left(\frac{t}{4.8728 \times 10^{11}}\right)}.6179$	Weibull	.6179 t ³⁸²¹ (4.8728 X10 ¹¹).6179	7.3325 x10 ¹¹
II	0-10,000	$1-\exp{-\left(\frac{t}{5.332 \times 10^9}\right)^{.8111}}$	Weibull	.8111 t1889 (5.332 x10 ⁹).8111	5.98 x10 ⁹
III	0-2,000	$1-\exp{-\left(\frac{t}{1.1943 \times 10^8}\right)}$	Exponential	8.4 X10 ⁻⁹	1.1943 X10 ⁸
III	0-5,000	$1-\exp{-\left(\frac{t}{153\ 398\ 200}\right)}^{964}$	Weibull	.964 t036 (153 398 200).964	1.56 X10 ⁸
III	0-10,000	$1-\exp\left(\frac{t}{619\ 088\ 092}\right).8451$	Weibull	.8451 t ¹⁵⁴⁹ (619 088 092) ·8451	6.76 x10 ⁸

Figure 19. Summary of Predicted Distribution

 $\lim_{n\to\infty} \mathbb{E}_{n}(\mathbb{R}^n) = \mathbb{E}_{n}(\mathbb{R}^n)$

the breakdown for the data in C.1 by vendor and C.3 has the breakdown by module function of quantities of micro circuits and failures. The vendor-failure relationship is not very strong. However, the function of input/output control has the most failures for all three failure categories. There is also a positive correlation of quantities of integrated circuits with quantities of failures.

Figure 20 has the calculations for the confidence intervals for the parameter of the exponential pdf. To determine confidence intervals for the parameters of the Weibull pdf is exceedingly more difficult. The procedure to follow could be that described by J. F. Lawless in the November 1978 issue of Technometrics.

6.3 Discussion of Significance

The procedure followed is typical of most studies of this nature. Screening was performed to get good independent data. With a type one error of .05, i.e., a significance level of .95, all time periods with the exclusion of 0-10,000 hr III (hard failures) would have the hypothesis of exponential pdf's accepted. The goodness of fit test that was used is that of Gnendenko which is the most powerful test for exponentiality for censored samples. A goodness of fit in censored samples for the Weibull pdf using the suggestions of Michael and Schucany of November 1979, Technometrics was done. For all cases, except 0-2,000 III and 0-10,000 III, the type one error is greater than .2 for rejecting the Weibull hypothesis. For 0-5,000 III the error would be

		Lower Limit	MTTF	Upper Limit
0-2000	I	2.75 X 10 ⁸	2.823 X 10 ⁸	1.74 X 10 ⁹
0-5000	I	1.49 X 10 ⁸	2.096 X 10 ⁸	3.20 X 10 ⁸
0-10,000) I	3.06 X 10 ⁸	6.6 X 10 ⁸	1.53 X 10 ⁹
0-2000	II	2.66 X 10 ⁸	5.17 X 10 ⁸	1.41 X 109
0-5000	II	3.59 X 10 ⁸	6.29 X 10 ⁸	1.37 x 10 ⁹
0-10,000)II	3.66 x 10 ⁸	6.6 X 10 ⁸	1.53 X 10 ⁹
0-2000	III	8.5 x 10 ⁷	1.19 x 10 ⁸	1.82 X 10 ⁸
0-5000	III	9.73 X 10 ⁷	1.28 X 10 ⁸	1.78 X 10 ⁸

Figure 20. 95% Confidence Intervals for Exponential pdf of Study

.05 and for 10,000 III it would be .01. Thus, there is good reason for accepting the Weibull pdf's.

The literature does not consider the problem of confidence when the magnitude of the population and failures observed are the size of our study. One could put little faith in the study if one considered the quantity failed—population size ratio of out study, 6.6 x 10⁻⁵, as unrepresentative of a mortality study. On the other hand, the most pessimistic MTTF determined in the study suggests we should have to wait 328 years to have 38% of the devices fail. Another factor that mades the conclusions of this study doubtful is the evolving state of the art. The microcircuits are constantly improving in reliability. The computer we ship today has a MTBF that is greatly improved over the "same" computer that was used in this study. Taking all of these factors into account, this study reflects the current state of the art of SSI digital devices operating in the field.

7.0 Conclusions

An intermittent failure is a detected malfunction of a logic net which resumes normal operation prior to the time needed to isolate the malfunctioning device. Due to the impracticability of having Sperry Univac's customers record the manifestation of intermittent failures, the phenomenon is not currently in Sperry Univac's reporting system. However, Sperry Univac engineers have determined which failure mechanism could be intermittent before they go hard and are reported.

To study the failure phenomenon three time periods -0-2000, 0-5,000, and 0-10,000 hour, were established, and three nonexclusive groups of computers were determined. These computers were in a repair environment. Failures in the study at the computer level included non-microcircuit devices. The best fitting distributions of time between intermittent failures are exponential for the 2000 and 5000 hour time periods. The distribution is Weibull for the 10,000 hour time period. The confidence intervals for MTBF indicate that the MTBF increases as the time period increases. This suggests that the occurence of intermittent failures is more frequent in the early life of the computer. The potential intermittent failure class shows a Weibull distribution of time between failure in the 2000 and 5000 hour time period. The failure rate for potential intermittents is increasing as the life of the computer increases. 10,000 hour time period appears to have a trimodal distribution for potentially intermittent failures. This may be due to the small number of computers in this time period.

For the same three time periods, a study of the digital micro circuits of the selected computer was made. The best fitting distributions for time to intermittent failure indicates that the rate of change of the intermittent failures rate is increasing. This means that a digital microcircuit is more likely to experience intermittent failure as the circuit gets older. The potential intermittent failure class shows a Weibull distribution of time to failure with a decreasing failure rate in all three time periods. The hard failure class shows the opposite phenomenon of the intermittent failure class. The rate of change of the hard failure rate is decreasing, which means the microcircuits are less likely to experience hard failures as they get older. These results apply up to an age of 10,000 hours for the selected computer and the microcircuits.

The data for the digital microcircuits occur in Type I censored form. Methods that are discussed in the literature regarding goodness of fit for censored samples were used. For all failure classes and time periods, with the exception of the 0-10,000 hour hard failure case, either the exponential or the Weibull distribution could be used as models. The final list of pdf's in Figure 18 is based upon an examination of Appendix C for the precision and accuracy of the goodness of fit. There is a positive correlation (.84) between the number of microcircuits in a module and the number of intermittent failures that module type has. The distribution of microcircuit intermittent and potentially intermittent failure, according to vendor is not uniform. One vendor who supplied 1.6 percent of the microcircuit population had 66.7 percent of the

intermittent failures.

It is questionable whether the available data regarding the number of failures, the time periods, and the populations of microcircuits are adequate to establish accurate predictability. After 10,000 hours, only .0096 percent of the population to this time period have experienced a failure. It would require, based upon the highest failure rate found, 29.9 years to have one percent of this population fail.

8.0 References

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List of Appendices to NASA Report NAS1-15574

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SPERVELINIVAC

APPENDIX A.1

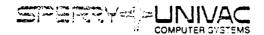
EQUIPMENT UTILIZATION REPORT

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UD1-3713

	SPERRY LINIVAC APPENDIX A.2	1 FMR NO. 2
	FAILURE/MALFUNCTION REPORT	□ 53689 o
WHAT FAILED	3 4 5 SITE 6 PROJ 7 FAIL DATE Y Y M M D D B CABINET TYPE 9 CAB S/NO. 10 ETM HOURS 11 REPAIR 12 TYPE REP'T MIN 2 RET 1 PRO OUT 32 RET 1 PRO OUT	ROFIT 25 DEBUG 31 SCREEN N IN 27 SPARES 22 CHECKOUT L 7 COMP 21 REPL S/NO.
WHAT WAS THE TROUBLE		CHECK () IF YES DIAG DETECT DIAG ISOLATE LOAD FAILURE HEAT SENSITIVE SHOCK SENSITIVE INTERMITTENT FAILURE VERIFIED SPARE AVAILABLE
-	(ORIGINATOR — DO NOT WRITE BELOW THIS LINE) 37 ANALYST NAME AND/OR Y Y M M D D	
ALYSIS	EMPLOYEE NUMBER	
AN		İ
FAULT FAILURE/REPAIR ANALYSIS		



FAILURE/MALFUNCTION REPORT

UDI-3180 (Rev. 8/76)

Originate the Failure/Malfunction Report (FMR) for each repair action, failure, or malfunction that involves a part, sub-assembly, chassis or unit of Univac aquepraent. It is the responsibility of the person who makes the repair, replacement or discovers a malfunction to originate the FMR. The form is divided into three sections: (1) WHAT FAILED — describes what failed, where when and who originated the form; (2) WHAT WAS THE TROUBLE — details what happened and what was done to correct the problem; and (3) FAULT-FAILURE/REPAIR ANALYSIS — describes the mode and cause of the failure.

The originator fills in the first two sections. Print the data using ball point pen to make the data clear on all carbon copies. Retain the golden-rod copy of the form and forward the FMR (3 copies or 2 if Customer Rep. copy is pulled on site) as listed:

NO PART INVOLVED MAILING ADDRESS

FMR WITH PART SHIPPING ADDRESS

SPERRY UNIVAC DSD, FIELD ENGR.. MS M2A01 P.O. BOX 3525 ST. PAUL, MINN. 55165 SPERRY UNIVAC DSD, RETURNED GOODS CRIB 2750 WEST 7TH BLVD. ST. PAUL, MINN, 55116

DETAILED INSTRUCTIONS FOR ORIGINATING THE FMR FORM

(1) WHAT FAILED SECTION

Place the hardpaper flap below the FMR set being filled out to prevent spoiling the sets below. Enter each digit clearly in the allotted space, as this data goes directly to Computer Data Bank via Scooe Input. Identify the letter I as "I"; numberic 1 as "I"; the letter O as "Ø"; rumberic zero as "O"; the letter S as "S"; the letter U as "U"; the letter Z as "Z"; the letter J as "J"; and capitalize all other letters. Do not enter any more letters or digits than a block allows or use any codes not authorized by this procedure. Enter only the data in each block for which information is available using the codes contained in the code tables. If a code is not available, enter the information in Block 36. Enter in these blocks:

Block No	. Block Title	Explanation	Block No	. Block Title	Explanation
6.	FROJ.	Project code (See codes - Block 6).	21	REPL S/N .	Serial Number of the replacement item.
7 8	FAIL DATE CABINET TYPE	Date failure was detected. Sperry Univac cabinet type	22	REF DOC NO.	Associated FMR/FR/FCO/EIR, Etc.
9	CAB S/N	number. Sperry Univac Manufacturing ser- lal number.	24	COMP. TYPE	Component or part type code when component or part is removed (See codes — Block 24).
10	E.T.M. (HOURS)	Elapsed Time Meter reading to nearest hour.	25	COMP. REF.	Component or part references designation (position) of falled
11	REPAIR MIN	Time to repair in minutes iso- late, repair and verify no logistics	26	COMPONENT	component or part. Sperry Univac part number of
12	TYPE REPORT	Type of report code (See codes if not preprinted.)			falled component or part when component or part is removed.
	TYPE OF FAILURE CHASSIS TYPE	Check applicable block.	27	DASH	Sperry Univac dash number of falled component or part.
•		Chassis type designation or code (See codes — Block 14).	28	VEND. CODE	Fill in vendor name in Block 36 if applicable.
15	CHASSIS S/N	Sperry Univac Manufacturing ser- ial number.	29	DATE CODE	Vendor date code as applicable
16	SUBA TYPE	Subassembly type code (See codes – Block 16).			when components or parts are removed.
17	SUBA S/N	Sperry Univac Manufacturing ser- lal number.	32	REPORTED BY	Employee number of person originating FMR.
18	SUBA REF.	Reference designation (position) from which falled subassembly	ĺ	LOCATION OR SITE	Name of location or site where failure occurred.
	SUBASSEMBLY PART NUMBER	was removed. Sperry Univac part number of falled subassembly.		CONTRACT NUMBER	Contract number covering unit on which maintenance or testing is performed.
20	DASH	Sperry Univac dash number of failed subassembly.		EMPLOYEE NAME	Initials and last name of person originating FMR.

NOTES: 1. When Manufacturing serial or type numbers are not available, enter customer nomenclature and serial number in Block 36.

2. Originator does not make entries in Blocks 3, 4, 5, 28, 30, 31, and 35. Make entries in Blocks 24 through 29 only when repairs

(2) WHAT WASTHE TROUBLE SECTION

occur at the component/part level.

- A. Failure Description Fill in a brief description of the symptoms of failure, operation routine, test and debugging procedure, errors noted, or other failure conditions observed. Give sufficient facts about the failure to adequately reconstruct the failure conditions for each level of assembly.
- B. Action Takes Fill in what was done to isolate this failure/malfunction and to repace or adjust the equipment to remove the problem. Trouble shooting notes such as switching of subassemblies, running diagnostic routines, testing for open or shorted pins, etc., are extremely resolution.
- C. Effect of Action Fill in what tests were run following the replacement of a failed part indicating the equipment is again operational. Also note part or assembly disposition, e.g., scrap, returned for analysis and/or repair with FMR.
- D. Maintenance Problems Enter problems which were encountered during this maintenance action. Notes as to availability of spares, replacements, damage, inadequate tools, and troubles in disassembling are helpful for future design considerations.

Appendix A.4. Field Failure Report Forms

(Account to the contract of th	Y=UNI	<u> </u>		EQUIP	MENT M	ALFUN	CTION	1 REPO
0 EQUIP NAME	33 SIFE/LOCATION				•		Lo	58 5 5
A SSITE	6 PROJ 7 FAIL DATI		INET TYPE	9 EQUIP S/N	10 ETM HOURS	11 REPAIR	12 REPAIR T	TYP 13 TYPE OF FAILUPE PRI II SEG
	MODOLAS SN 10 STAFE	17 SUBA SIN	18 SUBA REF	19 SUBASSE	MBLY PART NUMBE	in in	20 DASH	21 REPLACEVEN
22 RELATEDEMR	TAA9 EF TRA9 BE	T NUMBER		40 5: 15:4	32 NAME		1	<u> </u>
DA PROBLEM COMME	VIS:		1111	نـــــــــــــــــــــــــــــــــــ			1	
			•		•	•	•	CK (√) IF YE IAG DETECT
				•••			0 H	IAG ISOLATE DAD FAILURE EAT SENSITIV HOCK SENSITI ITERMITTENT
								 .
						•	•	
						•	•	
		FΔII I	IRF AN	ΙΔΙ Υςί	S DATA		. 1.	
2 0 24 000 25 000	REF 26 COMPONENT		27 0494		DATE COOE 30 7		ANALYST EM	PL NO.
		سنب						
35 ADDITIONAL DATA	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \					_		
	1 1 1 1 1		1111		<u> </u>	111	1 1 1 1	
39 ADDITIONAL DATA						111		
				111		111		
			1 1 1 1			111	1 1 1	
				<u> </u>			111	
							•	

APPENDIX A.5

DETAILED INSTRUCTIONS

EMR INSTRUCTIONS

COMPLETE ALL OPEN BLOCKS AS FOLLOWS (FRONT SIDE ONLY)

BLK. NO.	BLK TYPE	EXPLANATION
0 1	EQUIP NAME EMR NO. PR	Enter the equipment name, e.g., UYK-20, UYK-7, CP901, etc. Equipment Malfunction Report Number.
3 5	SITE CODE	Part Returned Y for YES, N for NO. Site Code — Enter the unique number for each site which can be obtained from
7 9	FAIL DATE EQUIPMENT S/N	Sperry Univac, STP Enter the date of the failure. Equipment Serial Number — Enter the complete customer serial number from the equipment
10	ETM HRS	Module Elapse Time Meter - Enter the ETM readings of the module in which the feet
11 12	REPAIR TIME REPAIR TYPE	occurred. If there is only one ETM, enter that reading, e.g., UYK-20. Enter the actual time to effect the repair, in minutes, NOT inclding parts acquisition. Check one of the blocks. EM — Emergency Maint., PM — Preventive Maint., FC — Field Change Order, IC — Installation and Checkout.
13 14	TYPE OF FAILURE MOD/CHASSIS TYPE	Check one for the type of failure, PRI — Primary Failure, SEC — Secondary Failure, Chassis Type, CPU — Central Processor Unit, IOC — Input/Output Controller, IOA — Input/ Output Adapter, MEM — Memory, DDM — Double Deuting Manager, CAR, Cabinet TS
15 16 17 18	MOD/CHASSIS S/N SUBA TYPE SUBASSY S/N SUBASSY REF	Chassis Serial Number — Enter the serial number of the module the failure occurred in. Enter subassembly type, i.e., PC. Enter Serial Number of the failed SUBASSY.
19 20 21	SUBASSY PART NO. DASH REPLACEMENT S/N	Enter the location of the failed SUBASSY, e.g., J32C. Enter the Univac part number for the failed major assembly not including dash number. Enter the dash number of the failed item in Block 19.
22 32	RELATED EMR NO.	Enter the replacement Part/Assy Serial No. Use only if secondary failure. Name of the individual making this report. If feedback is desired include mailing address on the reverce side of the first and the first area.
36	SITE/LOCATION PROBLEM COMMENTS	Enter the name of the first copy. Enter the name of the site and geographic location. Use this space for a narrative description of the failure to include problem description, how the problem was isolated (diagnostics, etc.), corrective action, and any difficulties in isolating the malfunction, If FCO or ECP installation, include the change two and number or expense.
39	PART TYPE PART NO. DASH NO.	other unusual circumstances. Enter part type, e.g., RES for Resistor, IC for Integrated Circuit. Enter the part number of the failed part (component) entered in Block 38. Enter a 3-digit dash number.

APPENDIX B.1 FAILURE DATA ACCORDING TO UNITS

	<u>Ir</u> 0-2000	ntermitte 0-5000	nt 0-10000		ally Inte	rmittent 0-10000	0-2000	<u>Total</u>	0-10000
250 500 750 1000 1250 1500 1750 2000 2250 2500 2750 3000 3250 4000 4250 4250 4750 5000	5 4 6 4 6 7 5	2 2 3 3 1 5 2 2 2 4 3 2 2 2 2 4 4 1	2 0 0 1 1 0 3 0 1 2 0 1 0 2 0 1	12 11 6 16 6 3 5 7	5 9 4 14 5 3 4 6 8 3 9 2 6 4 3 4 3 3 5 5	4 2 4 0 3 3 5 4 0 4 0 3 1 1 0 0 0 3 3	30 44 20 39 38 21 36 27	15 36 16 29 25 18 21 18 26 17 19 13 25 26 38 11 16 8 13	9 15 6 10 7 15 15 2 8 6 13 11 1 5 3 2 3
5500 5750 6000 6250 6500 6750 7000 7250 7500 7750 8000 8250 8500 8750 9000 9250 9500 9750			2000012210100000000			553331102222014520402		•	17 55 56 8 6 11 10 4 2 5 12 11 6 4 7 6 3

APPENDIX B.2
FAILURE TOTALS BY CATEGORY

	0 - 2000	2000 - 5000	5000 - 10000	Total
Intermittent	41	30	11	82
Potentially Intermittent	66	51	43	160
Hard	148	142	89	379
Totals	255	223	143	621

APPENDIX B.3

Confidence intervals of Parameters of Table 16

Description	90% C.I.	95% C.I.
Intermittent Failures 0-2000 hour	(6287 , 11193)	(6014, 11829)
Intermittent Failures 0-5000 hour	(9184, 14885)	(8767, 15630)
Potentially Intermittent (0-5000 hr)	(4873, 6830)	(4778, 7070)
Potentially Intermittent 0-10,000 hours	•	
0- 5,000 hours	(5302, 9277)	(5051, 9846)
5000 - 8250	(4478, 8562)	(4227, 9186)
8250 - 10000	(3373, 7479)	(3157, 8172)
Potentially Intermittent 0 - 2000 hr.	n = 169	
<u>Time</u>	5% Rank	95% Rank

<u>Time</u>	5% Rank	95% Rank
250	.0408	.119
500	0947	.1807
750	.1234	. 2208
1000	.2105	.3229
1250 ·	.2245	.3622
1500	.2578	.3815
1750	-288	.413
2000	.3263	.4567

Intermittent Failures n = 48

	11 - 40	
0 - 10,000 <u>Time</u>	5% Rank	95% Rank
250	.01	•-
500	•03	.09
750	.03	.15
1000	.03	•15
1250	.04	.15 .
1500	.06	.18
1750	.06	.21
2000	. 1	.21
2250	. 1	.28
2500	.12	.28 .3
2750	•15	
3000	.19	•35
3250	.19	•39
3750	•20	.39
4000	•24	•42
4250 .	•24	•46
4500	•26	.46
4750	.27	.48
5000	.29	• 5
5250	•33	.52
5500	•37	•56
5 750	•37	.61
6000	•37	.61
6250	•37	61
6500	.37	•61
6750	•39	.61
7000	•43	62
7250 .	•47	•66
7500	.49	• 7
8000	.51	•72
8250	.51	•74
8500	.51	•74
8750	.51	•74
9000	.51	•74
9250	.51	•74
9500	.51	•74
9750	.51	•74
10,000	.51	•74
		.74

• APPENDIX C.1
COMPARISON OF DISTRIBUTONS
0-2000 I

			2 2000 1				
TIME FAIL	OBSV. RELIABILITY	WEIBULL RELIABILITY	EXPONENTIAL RELIABILITY	CBSV. SURVIVORS	WEIBULL SURVIVORS	EXPONENTIAL SURVIVORS	
100 289 497 616 1017 1375 1450 1843 1938	.99999871 806 742 678 613 549 484 420 355 291	.99999901 814 742 706 603 524 508 432 414 406	.99999964 897 823 781 639 512 486 347 313	1552647 46 45 44 43 42 41 40 39 38	1552647.4 46.1 44.9 44.4 42.8 41.6 41.3 40.1 39.9 39.7	1552648.4 47.4 46.3 45.6 43.4 41.4 41 38.8 38.3 38.3	
			0-5000 I				
100 289 455 - 497 616 1017 1375 1843 1983 2268 2520 2622 2799 2802 3165 3428 3911 3949 4037 4142 4561 4603 4835	.99999823 734 646 558 469 381 293 204 116 028 .99998939 851 763 674 586 498 409 321 233 144 056 .99997968 879	.99999881 744 644 620 556 361 204 016 .99998979 962 855 764 728 666 665 542 455 299 287 260 227 098 086 016	.99999952 862 782 762 706 514 344 120 075 054 .99998918 797 749 664 663 490 364 134 116 074 024 .99997824 804	1131979 78 77 76 75 74 73 72 71 70 69 68 67 66 65 64 63 62 61 60 59	1131979.6 78.1 76.9 76.7 75.9 73.7 72 69.8 69.4 69.2 68.6 67.66.6 65.9 65.8 64.5 63.5 61.7 61.6 61.3 60.9 59.4 59.3	1131980.4 79.4 78.5 78.3 77.6 75.5 71.0 70.2 68.7 67.3 66.8 65.8 65.8 65.8 65.8 65.8 65.8	•
4840	703		693	56	58.5	54.8	
4992	761	015 •99997969	691 618	55 54	58.5 58	54.8 54	
1017 1938 1983 2622 2799 3911	.99999810 621 432 243 054 .99998864		-10000 I .99999846 706 699 603 576 408	528576 75 74 73 72	528576.2 74.9 74.8 73.5 73.2	76.1 75.4 75.4 74.9 74.7	
3949	675	753	408 402	71 70	70.5	73.8	
4603	486	407	303	70 69	70.4 68.5	73.8 73.3	

0-2000 II

TIME	OBSV.	WEIBULL	EXPONENTIAL	OBSV.	WEIBULL	EXPONENTIA
FAIL	RELIABILITY	RELIABILITY	RELIABILITY	SURVIVORS	SURVIVORS	SURVIVORS
186	.99999935	.99999894	.99999964	1552648	1552647.3	1552648.4
195	806	890	962	46	47.3	48.4
291	742	855	943	45	46.7	48.1
919	677	677	822	44	43.9	46.2
952	613	669	816	43	43.8	46.1
1698	549	503	671	42	41.2	43.9
186 195 291 919 952 1698 2729 2730 3149	.99999911 734 646 558 469 381 293 204 116	0.99999848 844 800 593 584 405 203 203 129	-5000 II .99999967 965 485 837 831 700 517 517 443	1131980 78 77 76 75 74 73 72 71	1131979.2 79.2 78.7 76.3 76.2 74.2 71.9 71.9 71.1	1131980.6 80.6 80.4 79.1 79 77.6 75.5 75.5
291	.99999810	.99999871	10000 II	528576	528576.3	528576.7
952	621	663	.999999955	75	75.2	76.2
1698	432	461	743	74	74.1	75.6
2729	243	209	586	73	72.8	74.8
2730	054	208	586	72	72.8	74.8
3149	.99998864	111	523	71	72.3	74.4
5320	675	.99998641	194	70	69.8	72.7
5960	486	509	097	69	69.1	72.2

0-2000 III

TIME	OBSV.	WEIBULL	EXPONENTIAL RELIABILITY	OBSV. SURVIVCRS	WEIBULL SURVIVORS	EXPONENTIAL SURVIVORS
TIME FAIL 287 295 299 306 333 341 352 412 423 437 465 531 573 646 926 1000 1014 1020 1117 1162 1245 127	RELIABILITY .99999935 871 806 742 677 613 549 484 420 355 291 227 162 098 033 .99998969 905 840 776 711 647 583	RELIABILITY .99999770 762 758 749 725 717 706 644 632 617 587 515 468 385 048 .99998955 937 929 804 746 636 593	EXPONENTIAL RELIABILITY .99999759 753 749 743 721 714 705 655 645 634 610 555 520 459 224 162 151 145 064 027 .99998957 930 643		WEIBULL SURVIVORS 1552645.4 45.3 45.2 45.1 44.7 44.6 44.4 43.4 43.2 43 42.6 41.4 40.7 39.4 34.2 32.7 32.5 32.3 30.4 29.5 27.8 27.1 19.8	1552645.2 45.1 45.1 45.4 44.6 44.5 44.4 43.6 43.5 43.3 42.9 42.9 41.5 40.6 36.9 36.9 35.8 35.7 34.4 33.8 32.8 32.8 32.9
1620 1630 1698 1853	518 454 389 325	122 108 012 .99997789	643 635 578 448	25 24 23	19.6 18.1 14.6	27.8 26.9 24.9

0-5000 III

FAIL TIME	OBSV. RELIABILITY	WEIBULL	EXPONENTIAL	OESV.	WEIBULL	EXPONENTIAL
			RELIABILITY	SURVIVORS	SURVIVORS	SURVIVORS
295 299	.99999911	.99999691	.99999753	1131980	1131977.5	1131978.2
299 306	823	687	749	79	77.4	78.1
341	734 646	680	743	78	77.3	78.1
352	558	644	714	. 77	76.9	77.7
373	469	633	705	76	76.8	77.6
423	381	612	687	. 75	76.6	77.4
437	293	562	645	74	76	76.9
465	204	548 521	634	73	75.8	76.8
573	116		610	72	75.5	76.5
646	028	414 342	520	, 71	74.3	75.5
926	.99998939	342 069	459	70	73.5	74.8
1000	851	.99998998	224	69	70.4	72.2
1014	763	984	162	68	69.6	71.5
1020	674	978	151	67	69.5	71.4
1117	586	885	145	66	69.4	71.3
1162	498	841	064	65	68.3	70.4
1277	409	731	027 •99998930	64	67.8	69.9
1620	321	404	643	63	66.6	68.8
1630	233	395	635	62	62.9	65.6
1698	144	330	578	61	62.8	65.5
1853	056	184	448	60	62.1	64.9
2032	.99998968	015	298	59 58	60.4	63.4
2065	879	.99997984	271	58 57	58.5	61.7
2333	791	732	046	5 / 5 6	58.1	61.4
2750	703	343	.99997697	55	55.3	58.8
2799	610	297	656	54	50.9	54.9
2843	526	256	619	53	50.4	54.4
2910	438	194	563	53 52 .	49.9	54
2971	349	137	512	51	49.2	53.4
3021	261	091	470	50	48.5	52.8
3032	173	080	461	49	48 47.9	52.3
3055	084	059	442	48		52.2
3116	.99996996	002	391	47	47.7 47	52
3146	908	.99996975	365	46	46.7	51.4
3426	819	716	131	45	43.8	51.1
3430	731	712	128	44	43.7	48.5
3561 3658	643	591	018	43	42.4	48.5
4015	554	501	.99996937	42	41.4	47.2
4218	466	173	· 383	41	37.6	46.3
4218 4342	378	.99995987	468	40	35.5	42.9 41
4542 4545	289	873	364	39	34.2	39.8
4345 4736	201	687	194	38	32.1	39.8 37.9
	113	513	034	37	30.2	36.1

0-10000 III

FAIL TIME	OBSV. RELIABILITY	WEIBULL RELIABILITY	EXPONENTIAL RELIABILITY	OBSV. SURVIVORS	WEIBULL SURVIVERS	EXPONENTIA: SURVIVORS
295	.99999810	.99999545	.99999804	528576	528574.5	E20575 0
299	621	540	802	75	74.5	528575.9
341	432	486	774	74	74.2	75.9 75.8
423	743	383	719	. 73	73.7	75.8 75.5
437	054	366	710	72	73.6	75.4
646	.99998864	118	572	71	72.3	74.7
952	675	.99998777	369	70	70.5	73.6
1020	486	703	324	69	70.1	73.4
1117	297	600	260	68	69.6	73.4
1277	108	432	154	67	68.7	72.5
1620	.99997918	083	.99998927	66	66.8	71.3
1630	729	073	920	65	66.8	71.2
1698	540	006	875	64	66.4	71
1853	351	.99997853	773	63	65.6	70.5
2065	162	647	632	62	64.5	69.7
2729	.99996973	022	192	61	61.2	67.4
2730	838	021	192	60	61.2	67.4
2786	594	.99996970	155	59	60.9	67.2
2843	405	917	117	58	60.7	67
3021	216	755	.99997999	57	59.8	66.4
3032	027	745	992	56	59.7	66.3
3149	.99995837	639	914	55	59.2	65.9
3426	648	391	731	54	57.9	65
3430	459	387	728	53	57.9	65
4218	270	.99995698	207	52	54.2	62.2
4342	081	591	124	51	53.6	61.8
4736	.99994891	255	.99996864	50	51.9	60.4
5405	702	.99994695	421	49	48.9	58.1
6269	513	.99993987	.99995849	48	45.2	55
7444	324	047	071	47	40.2	50.9
7709 8645	135	.99992838	.99994895	46	39.1	50.0
9542	.99993946	110	275	45	35.2	46.7
9610	756 567	.99991424	.99993681	44	31.6	43.6
9659	567	372	636	43	31.4	43.3
7039	378	335	604	42	31.2	43.1

APPENDIX C.2 Proportion Breakdown of Microcircuit Types by Vendor

The 18 microcircuit types that were previously analyzed for pdfs of time to failure and which determined a study population of 1552649 relate to the vendor as follows:

PROPORTION BREAKDOWN BY VENDOR

VENDOR	Proportion of Population	Qty of Intermittent and Potentially Intermittent Failures	Proportion of Intermittent and Potentially Intermittent Failures
. 1	.2733	8	.205
2	.2933	3	.077
3	.3653	2	.051
4	.04	0	o ·
5	.0166	26	.667
25	.0075	0	0
7 8	.004	. 0	0

	Total Qty in Population	Proportion of Total Population			oport: y Vend			} t	Fai y V)-20	end	or			by	ilu Ven	dor	•	5(Fa by 000-	il. Ve:	ıdoı	r
Vendor			1	2	. 3	4	5	1	2	3	4	5	1	2	3	4	5	1	2	3	4	5
Microcircuit	•			,																		
1	272492	.1755	.206	.322	.472			1	0	0			3		0			0	0	0		
2	1055481	.67,97	.276	.317	.407			1	3	0			0	0	0			0		0		
3,	59011	.038	.546	.376		,	.078	2	0			9	0	0			10	0	0			1
4	69646	.045	.296	.141	.380		.183	0	ò	0		3	0	0	1		3	1	0	1		
•																						

The remaining 14 part types had no failures of an intermittent and Potentially Intermittent nature and made up 6.19% of the population.

APPENDIX C.3

Quantity of Digital Microcircuits per Chassis

	IC Per SingleChassis			
Power Supply	7	1372		
Input Output Controller	2544	432480		
Input Output Adapter	246	57737		
Central Processing Unit	3658	588938		
Core Memory	781	412368		
Film Memory	866	59754		
TOTALS	8102	1552649		

Grid of Microcircuit Failure by Chassis Function

	Intermittent	Potentially Intermittent	<u> Hard</u>	
Power Supply	0	· 0	0	
Input Output Controller	14	· 5	15	
Input Output Adapter	. 0	0	13	
Central Processor Unit	8	1	13	
Core Memory	6	8	11	
Film Memory	0	0	12	

1. Report No. NASA CR-159268	2. Government Acces	ssion No.	3. Reci	pient's Catalog No.	
4. Title and Subtitle Study of Intermitte	ure Data :	in Ju	5. Report Date June 1980		
Digital Electronics		6. Perfe	orming Organization Code		
7. Author(s)			8. Perfe	8. Performing Organization Report No.	
Edward J. O'Neill and James R. Halverson			10. Worl	10. Work Unit No.	
9. Performing Organization Name Sperry Univac	and Address	-			
Univac Park P. O. Box 3525				11. Contract or Grant No. NAS1-15574	
St. Paul, Minnesota 55165				13. Type of Report and Period Covered	
12. Sponsoring Agency Name and Address National Aeronautics and Space Administration				ntractor Report	
Washington, DC 20546			14. Spor	nsoring Agency Code	
15. Supplementary Notes NASA Project Engine Hampton, Virginia	eer, Salvatore Bavuso, 1 23665	Langley Re	esearch Center	•	
failures in digital was designed for she which were classiff intermittent, poter respect to computer 0-10,000 hours. The level (SSI Technology)		as made us illure data ms and the r hard. I es of 0-2, e computer	sing data from a consisted of eir likelihood cach class was 000 hours, 0-1 tevel as well	a computer which actual field failures of having been studied with 5,000 hours and las the microcircuit	
	nat as age increases, the contract of the cont	ie quasi-i	ntermittent i	allure fate increases	
•					
17 Key Words (Suspected by Aust	nodel 1	Tag Dissibut		······································	
7. Key Words (Suggested by Author(s)) Intermittent failures		18. Distribution Statement • Unclassified - Unlimited			
Reliability Field Failure Data		STAR Category 38			
19. Security Classif, (of this report)	Security Classif. (of this report) 20. Security Classif. (of this		21. No. of Pages	22. Price*	
Unclassified	Unclassified	-	66		

End of Document